

Application No. 09/756,140

Art Unit 1755

May 21, 2004

Supplemental Reply to Office Action of August 26, 2003

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the present application.

Listing of Claims:

1. (Currently Amended) ~~An abrasive~~ A polishing composition for metal comprising an oxidizing agent, water and a polymer particle having a functional group that traps a metal ion, wherein the functional group that traps a metal ion is iminodiacetic acid.

2-4. (Canceled)

5. (Currently Amended) ~~The abrasive for metal~~ polishing composition according to claim 1, wherein ~~the particle having a functional group that traps a metal ion is a particle comprising an ion exchange resin,~~ and the average particle diameter of the particle is 1.0 μm or less.

6-7. (Canceled)

8. (Currently Amended) A process for producing the an abrasive for metal comprising a polymer particle having a functional group that traps a metal ion, wherein the functional group that traps a metal ion is iminodiacetic acid, ~~according to claim 5,~~ wherein the process comprises

Application No. 09/756,140

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wet-milling ~~an ion-exchange resin~~, the polymer having a functional group that traps a metal ion.

9. (Currently Amended) A process for producing the an abrasive for metal comprising a polymer particle having a functional group that traps a metal ion, wherein the functional group that traps a metal ion is iminodiacetic acid, according to claim 5, wherein the process comprises dry-milling and then wet-milling ~~an ion-exchange resin~~, the polymer having a functional group that traps a metal ion.

10. (Canceled)

11. (Previously Presented) The abrasive for metal according to claim 1, wherein the metal is copper or copper alloy.

12-13. (Canceled)

14. (Currently Amended) The polishing composition for metal according to ~~claim 12,~~ claim 1, wherein the oxidizing agent is hydrogen peroxide.

Application No. 09/756,140

Art Unit 1755

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15. (Currently Amended) The polishing composition for metal according to claim ~~12~~ 1, wherein the composition further comprises at least one selected from the group consisting of a spherical particle, benzotriazole and a benzotriazole derivative.

16. (Currently Amended) A process for polishing a metal by chemical mechanical polishing, wherein the process is conducted by using the polishing composition for metal according to claim ~~12~~ 1.

17. (Previously Presented) The process according to claim 16, wherein the metal is copper or copper alloy.

18-19. (Canceled)